



Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 273117US0PCT			SERIAL NO. 10/542,358	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Yasuaki YOKOYAMA, et al.				
				FILING DATE July 14, 2005			GROUP	
U.S. PATENT DOCUMENTS								
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE	
	AA							
	AB							
	AC							
	AD							
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
	AL							
	AM							
	AN							
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO			
/MLS/	AO	2002-175983	06/21/02	JP(with English abstract)		NO		
/MLS/	AP	95-04168	02/09/95	WO		NO		
	AQ							
	AR							
	AS							
	AT							
	AU							
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)								
/MLS/	AV	Yoshihiro HAMAKAWA and Yukinori KUWANO: "Advanced Electronics Series I-3 "Solar Energy Optics, Solar Cell", the sixth impression of the first editor, Baifukan, pages 74, 75, 314, February 10, 2000. (with partial English translation)						
/MLS/	AW	S. S. COHEN et al.: "Al-0.9% Si/Si Ohmic Contacts to Shallow Junctions", J. Electrochem. Soc.: SOLID-STATE SCIENCE AND TECHNOLOGY, pages 1335-1338, June 1982.						
/MLS/	AX	John K. RUFF and M. Frederick HAWTHORNE: "The Amine Complexes of Aluminum Hydride. I.", AMINE COMPLEXES OF ALUMINUM HYDRIDE, Vol. 82, pages 2141-2144, May 5, 1960.						
/MLS/	AY	G. W. FRASER et al.: "Aluminium Hydride Adducts of Trimethylamine: Vibrational Spectra and Structure", pages 3742-3747, 1963.						
/MLS/	AZ	Jerry L. ATWOOD et al.: "Tertiary Amine Stabilized Dialane", J. Am. Chem. Soc., Vol. 113, pages 8183-8186, 1991.						
Examiner					<input type="checkbox"/> Additional References sheet(s) attached			
/Mark L. Shevin/					Date Considered 03/04/2008			

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.